

PS9513, PS9513L1, PS9513L2, PS9513L3

1 Mbps, OPEN COLLECTOR OUTPUT, FOR INTELLIGENT POWER MODULE DRIVE 8-PIN DIP HIGH-SPEED PHOTOCOUPLER

R08DS0126EJ0203 Rev.2.03 Oct 29, 2018

DESCRIPTION

The PS9513, PS9513L1, PS9513L2 and PS9513L3 are optically coupled isolators containing an AlGaAs LED on the input side and a photo diode and a signal processing circuit on the output side on one chip.

The PS9513 is designed specifically for high common mode transient immunity (CMR) and low pulse width distortion with operating temperature. It is suitable for IPM drive.

The PS9513L1 is lead bending type for long creepage distance.

The PS9513L2 is lead bending type for long creepage distance (Gull-wing) for surface mount.

The PS9513L3 is lead bending type (Gull-wing) for surface mounting.

FEATURES

- Long creepage distance (8 mm MIN.: PS9513L1, PS9513L2)
- High common mode transient immunity (CM_H, CM_L = ± 15 kV/ μ s MIN)
- High-speed response ($t_{PHL} = 500 \text{ ns MAX.}$, $t_{PLH} = 750 \text{ ns MAX.}$)
- Propagation Delay Difference $(t_{PLH} t_{PHL} = 270 \text{ ns TYP.})$
- Pulse width distortion ($|t_{PHL} t_{PLH}| = 270 \text{ ns TYP.}$)
- Open collector output
- Ordering number of tape product : PS9513L2-E3 : 1 000 pcs/reel

: PS9513L3-E3 : 1 000 pcs/reel

- Pb-Free product
- Safety standards
- UL approved: UL1577, Double protection
- CSA approved: CAN/CSA-C22.2 No.62368-1, Reinforced insulation
- BSI approved: BS EN 62368-1, Reinforced insulation
- - SEMKO approved: EN 62368-1, IEC 62368-1, Reinforced insulation
- NEMKO approved: EN 62368-1, Reinforced insulation
- - DEMKO approved: EN 62368-1, Reinforced insulation
- FIMKO approved: EN 62368-1, Reinforced insulation
- VDE approved: DIN EN 60747-5-5 (Option)

PIN CONNECTIONS (Top View) 8 7 6 5 1. NC 2. Anode 3. Cathode 4. NC 5. GND 6. Vo 7. NC 1 2 3 4 8. Vcc

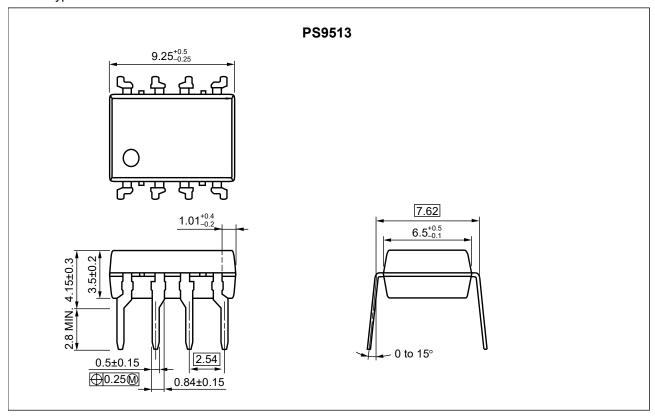
APPLICATIONS

- IPM Driver
- General purpose inverter

Start of mass production Jun-2006

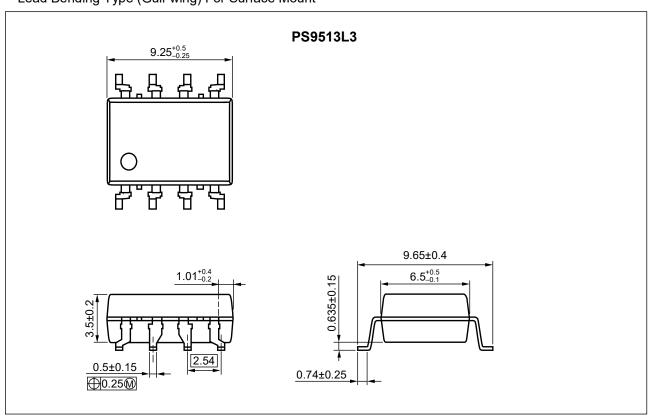
PACKAGE DIMENSIONS (UNIT: mm)

DIP Type

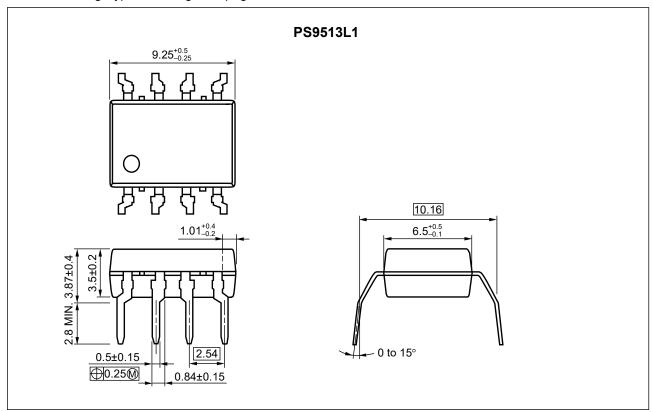


Weight: 0.55g (typ.)

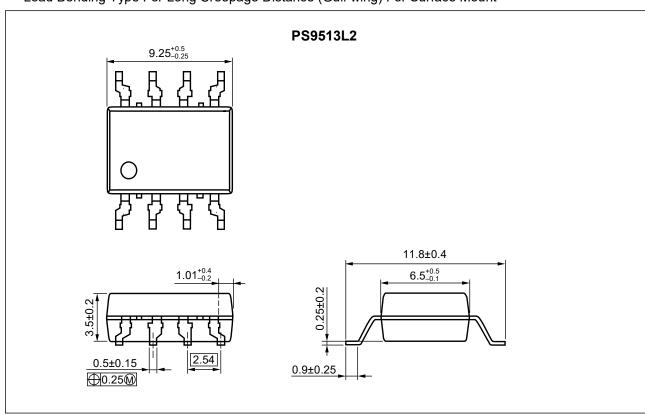
Lead Bending Type (Gull-wing) For Surface Mount



Lead Bending Type For Long Creepage Distance



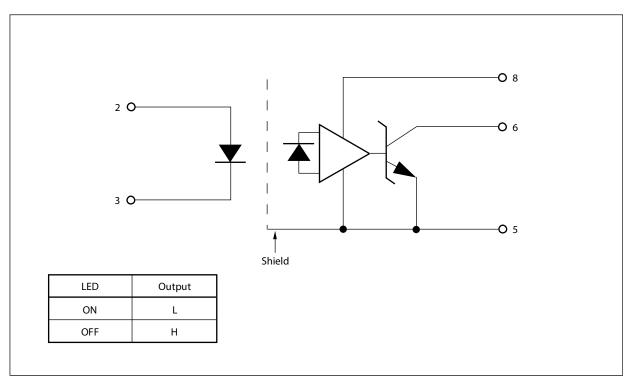
Lead Bending Type For Long Creepage Distance (Gull-wing) For Surface Mount



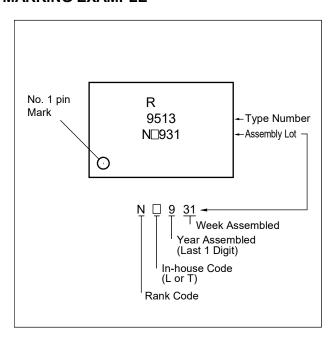
PHOTOCOUPLER CONSTRUCTION

Parameter	PS9513, PS9513L3	PS9513L1, PS9513L2
Air Distance (MIN.)	7 mm	8 mm
Creepage Distance (MIN.)	7 mm	8 mm
Isolation Distance (MIN.)	0.4 mm	0.4 mm

FUNCTIONAL DIAGRAM



MARKING EXAMPLE



ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number*1
PS9513	PS9513-AX	Pb-Free	Magazine case 50 pcs	Standard products	PS9513
PS9513L1	PS9513L1-AX	(Ni/Pd/Au)		(UL, CSA, BSI,	PS9513L1
PS9513L2	PS9513L2-AX			SEMKO, NEMKO,	PS9513L2
PS9513L3	PS9513L3-AX			DEMKO, FIMKO	PS9513L3
PS9513L2-E3	PS9513L2-E3-AX		Embossed Tape 1 000 pcs/reel	approved)	PS9513L2
PS9513L3-E3	PS9513L3-E3-AX				PS9513L3
PS9513-V	PS9513-V-AX		Magazine case 50 pcs	UL, CSA, BSI,	PS9513
PS9513L1-V	PS9513L1-V-AX			SEMKO, NEMKO,	PS9513L1
PS9513L2-V	PS9513L2-V-AX			DEMKO, FIMKO,	PS9513L2
PS9513L3-V	PS9513L3-V-AX			DIN EN 60747-5-5	PS9513L3
PS9513L2-V-E3	PS9513L2-V-E3-AX		Embossed Tape 1 000 pcs/reel	approved	PS9513L2
PS9513L3-V-E3	PS9513L3-V-E3-AX				PS9513L3

Notes*: 1. For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

	Parameter	Symbol	Ratings	Unit
Diode	Forward Current *1	IF	25	mA
	Reverse Voltage	VR	5.0	V
Detector	Supply Voltage	Vcc	−0.5 to +25	V
	Output Voltage	Vo	−0.5 to +25	V
	Output Current	lo	15	mA
	Power Dissipation *2	Pc	100	mW
Isolation V	oltage *3	BV	5 000	Vr.m.s.
Operating Ambient Temperature		TA	-40 to +100	°C
Storage Te	emperature	T _{stg}	−55 to +125	°C

Notes*: 1. Reduced to 0.33 mA/°C at T_A = 70°C or more.

- 2. Reduced to 2.0 mW/°C at $T_A = 70$ °C or more.
- 3. AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output. Pins 1-4 shorted together, 5-8 shorted together.

RECOMMENDED OPERATING CONDITIONS

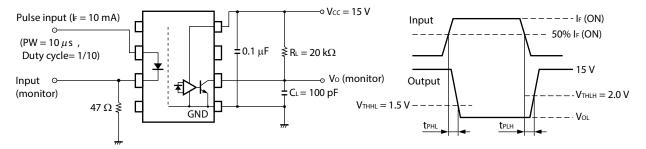
Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Forward Current	lF	10		20	mA
Output Voltage	Vo	0		20	V
Supply Voltage	Vcc	4.5	15	20	V
Input Voltage	V _F	0		0.8	V

ELECTRICAL CHARACTERISTICS ($T_A = -40 \text{ to } +100^{\circ}\text{C}$, $V_{CC} = 15 \text{ V}$, unless otherwise specified)

	Parameter	Symbol	Conditions	MIN.	TYP.*1	MAX.	Unit
Diode	Forward Voltage	VF	I _F = 10 mA	1.3	1.65	2.1	V
	Reverse Current	l _R	V _R = 3 V			200	μA
	Terminal Capacitance	Ct	V = 0 V, f = 1 MHz, T _A = 25°C		30		pF
Detector	Low Level Output Voltage	Vol	I _F = 10 mA, I _{OL} = 2.4 mA		0.13	0.6	٧
	High Level Output Current	Іон	$V_{CC} = 20 \text{ V}, V_F = 0.8 \text{ V}$		1.0	50	μA
	High Level Supply Current	Іссн	Vcc = 20 V, V _F = 0.8 V, V ₀ = open		0.6	1.3	mA
	Low Level Supply Current	Iccl	Vcc = 20 V, I _F = 10 mA, V ₀ = open		0.6	1.3	mA
Coupled	Threshold Input Current $(H \rightarrow L)$	I _{FHL}	Vo = 0.8 V, Io = 0.75 mA		0.86	5.0	mA
	Current Transfer Ratio (Ic/I _F)	CTR	$I_F = 10 \text{ mA}, V_O = 0.6 \text{ V}$	44	110		%
	Isolation Resistance	Rı-o	V _{I-O} = 1 kV _{DC} , RH = 40 to 60%, T _A = 25°C	10 ¹¹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz, T _A = 25°C		0.7		pF
	Propagation Delay Time $(H \rightarrow L)^{*2}$	t PHL	I _F = 10 mA, R _L = 20 kΩ, C _L = 100 pF, V _{THHL} = 1.5 V, V _{THLH} = 2.0 V		250	500	ns
	Propagation Delay Time $(L \rightarrow H)^{*2}$	t _{PLH}			520	750	
	Propagation Delay Difference	t _{РІН} —t _{РНІ}		-200	270	650	
	Pulse Width Distortion (PWD)*2	t _{РНL} —t _{РLН}			270	650	
	Common Mode Transient Immunity at High Level Output*3	СМн	$T_{A} = 25^{\circ}\text{C}, \ I_{F} = 0 \ \text{mA}, \ V_{O} > 3.0 \ \text{V}, \\ V_{CM} = 1.5 \ \text{kV}, \ R_{L} = 20 \ \text{k}\Omega, \\ C_{L} = 100 \ \text{pF}$	15			kV/ <i>μ</i> s
	Common Mode Transient Immunity at Low Level Output*3	CM∟	$T_{A} = 25^{\circ}C, \ I_{F} = 10 \ mA, \ V_{O} < 1.0 \ V, \\ V_{CM} = 1.5 \ kV, \ R_{L} = 20 \ k\Omega, \\ C_{L} = 100 \ pF$	-15			kV/μs

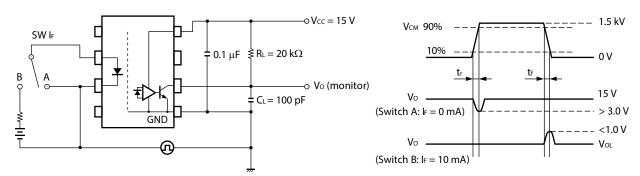
Notes*: 1. Typical values at $T_A = 25$ °C.

2. Test circuit for propagation delay time



Remark CL includes probe and stray wiring capacitance.

3. Test circuit for common mode transient immunity



Remark CL includes probe and stray wiring capacitance.

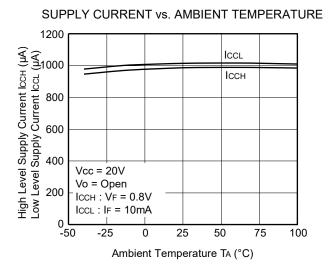
USAGE CAUTIONS

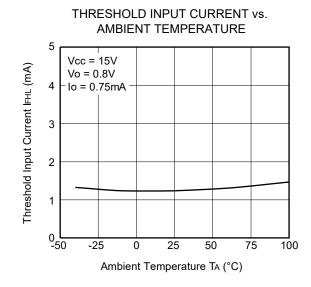
- 1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.
- 2. By-pass capacitor of more than $0.1~\mu F$ is used between V_{CC} and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than 10 mm.
- 3. Pins 1, 4 (which is an NC*1 pin) can either be connected directly to the GND pin on the LED side or left open. Also, Pin 7 (which is an NC*1 pin) can either be connected directly to the GND pin on the detector side or left open.

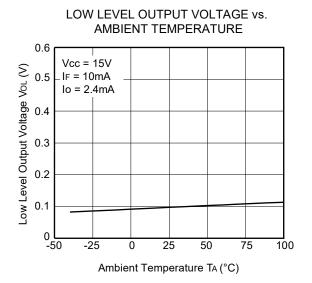
Unconnected pins should not be used as a bypass for signals or for any other similar purpose because this may degrade the internal noise environment of the device.

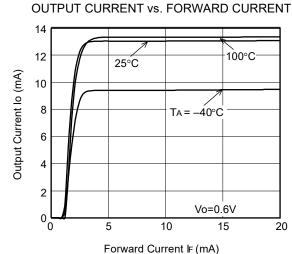
- *1 NC: Non-Connection (No Connection)
- 4. Avoid storage at a high temperature and high humidity.
- 5. Do not use adhesives or coating materials including halogens to fix this device.

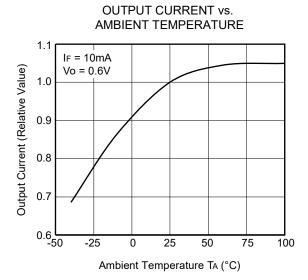
TYPICAL CHARACTERISTICS ($T_A = 25^{\circ}$ C unless otherwise specified)

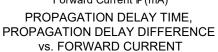


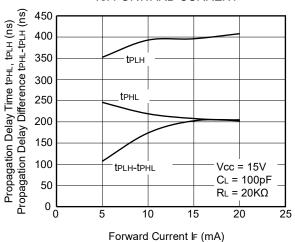






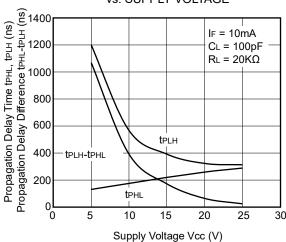




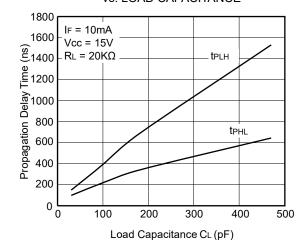


Remark The graphs indicate nominal characteristics.

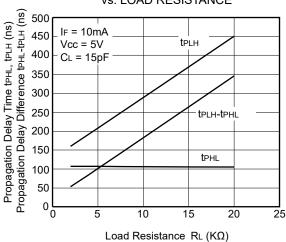
PROPAGATION DELAY TIME, PROPAGATION DELAY DIFFERENCE vs. SUPPLY VOLTAGE



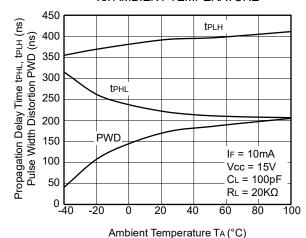
PROPAGATION DELAY TIME vs. LOAD CAPACITANCE



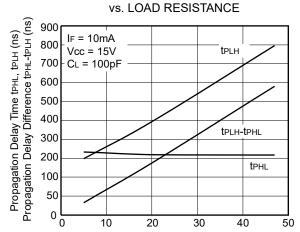
PROPAGATION DELAY TIME, PROPAGATION DELAY DIFFERENCE vs. LOAD RESISTANCE



PROPAGATION DELAY TIME, PULSE WIDTH DISTORTION vs. AMBIENT TEMPERATURE



PROPAGATION DELAY TIME, PROPAGATION DELAY DIFFERENCE



20

10

Load Resistance RL (KΩ)

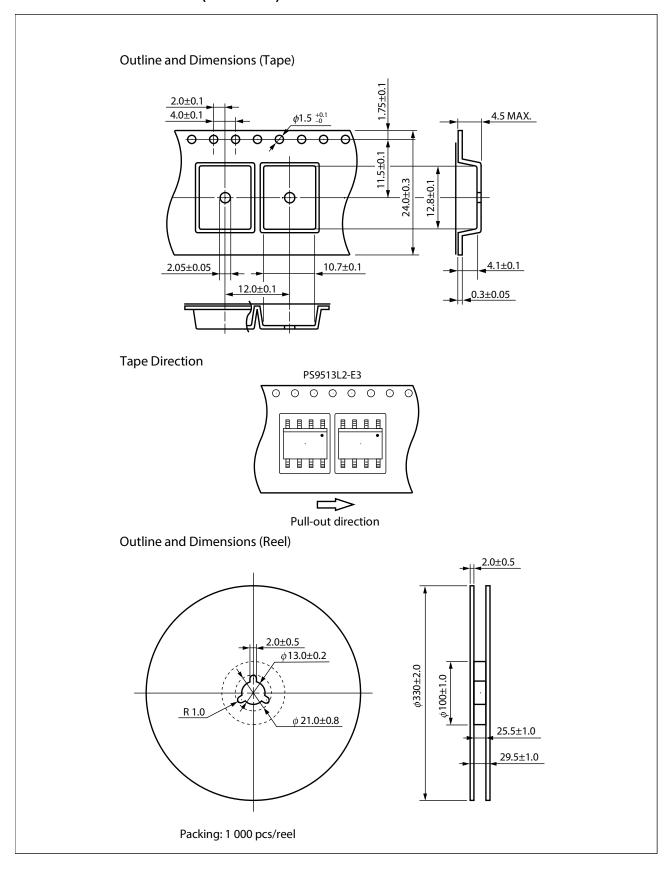
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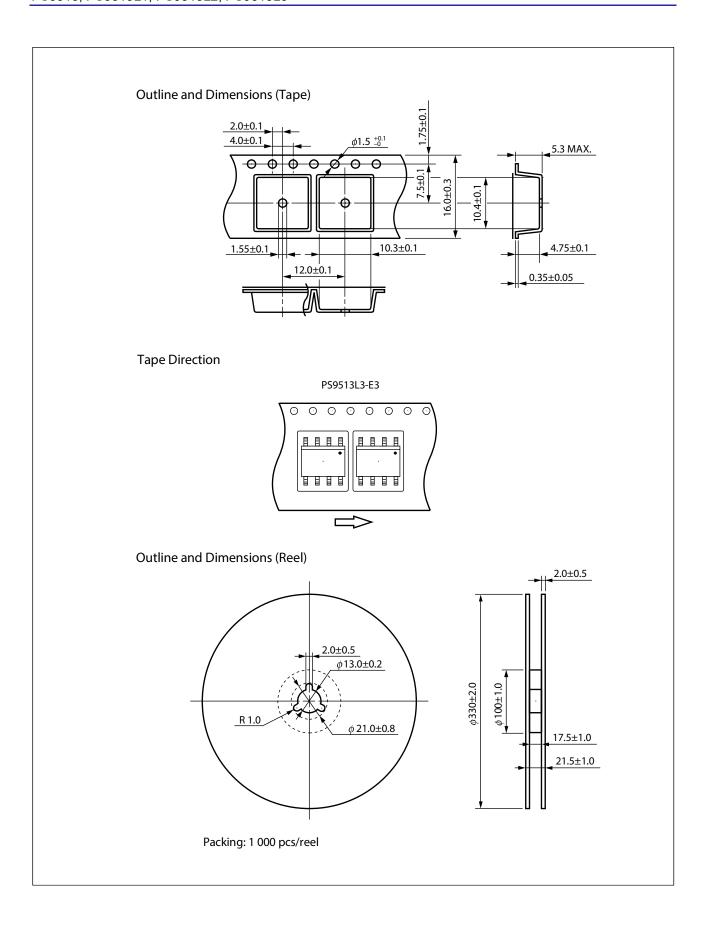
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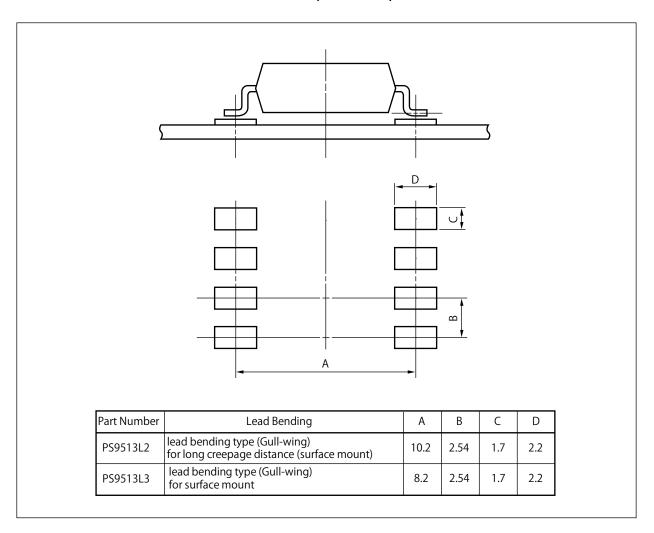
Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT: mm)





RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



NOTES ON HANDLING

- 1. Recommended soldering conditions
 - (1) Infrared reflow soldering

Peak reflow temperature
 260°C or below (package surface temperature)

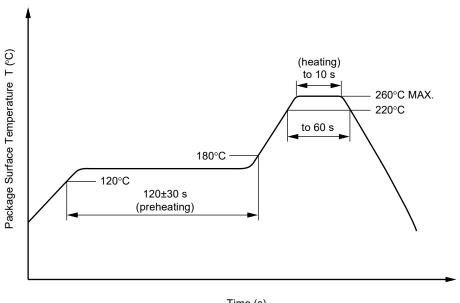
Time of peak reflow temperature
 Time of temperature higher than 220°C
 10 seconds or less
 60 seconds or less

• Time to preheat temperature from 120 to 180°C 120±30 s

Number of reflowsFluxRosin flu

Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



Time (s)

(2) Wave soldering

• Temperature 260°C or below (molten solder temperature)

Time 10 seconds or less

• Preheating conditions 120°C or below (package surface temperature)

Number of times
 Flux
 One (Allowed to be dipped in solder including plastic mold portion.)
 Rosin flux containing small amount of chlorine (The flux with a maximum

chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by Soldering Iron

Peak Temperature (lead part temperature)
Time (each pins)
350°C or below
3 seconds or less

• Flux Rosin flux containing small amount of chlorine

(The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

- (a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead
- (b) Please be sure that the temperature of the package would not be heated over $100\,\square\text{C}$
- (4) Cautions
 - Fluxes

Avoid removing the residual flux with freon - based and halogens - based (chlorine-based) cleaning solvent .

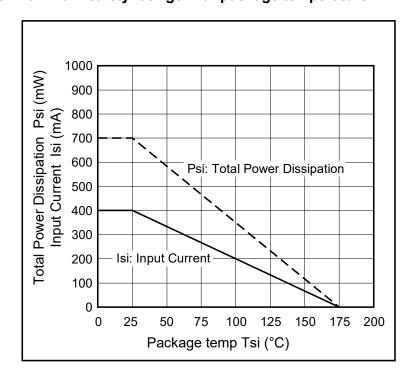
2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between V_{CC} -GND at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

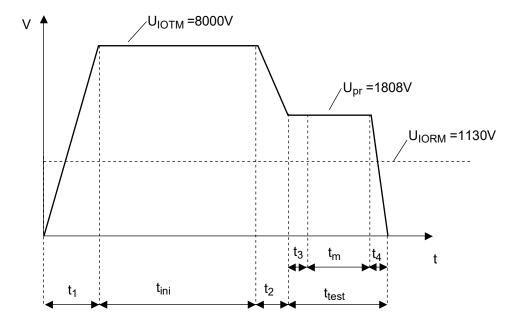
SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Rating	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		40/100/21	
Dielectric strength maximum operating isolation voltage Test voltage (partial discharge test, procedure a for type test and random test) $U_{Pr} = 1.6 \times U_{IORM}$, $P_d < 5$ pC	UIORM Upr	1 130 1 808	V _{peak} V _{peak}
Test voltage (partial discharge test, procedure b for all devices) $U_{pr}=1.875\times U_{IORM}, P_d<5\; pC$	Upr	2 119	V _{peak}
Highest permissible overvoltage	Uютм	8 000	V _{peak}
Degree of pollution (DIN EN 60664-1 VDE 0110 Part 1)		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303 Part 11))	CTI	175	
Material group (DIN EN 60664-1 VDE 0110 Part 1)		III a	
Storage temperature range	T _{stg}	-55 to +125	°C
Operating temperature range	TA	-40 to +100	°C
Isolation resistance, minimum value V _{IO} = 500 V dc at T _A = 25°C V _{IO} = 500 V dc at T _A MAX. at least 100°C	Ris MIN. Ris MIN.	10 ¹² 10 ¹¹	Ω Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve) Package temperature Current (input current I _F , Psi = 0) Power (output or total power dissipation)	Tsi Isi Psi	175 400 700	°C mA mW
Isolation resistance V _{IO} = 500 V dc at T _A = Tsi	Ris MIN.	10 ⁹	Ω

Dependence of maximum safety ratings with package temperature



Method a) Destructive Test, Type and Sample Test



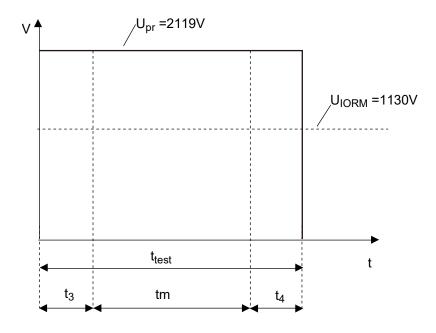
 $t_1, t_2 = 1 \text{ to } 10 \text{ sec}$

 $t_3, t_4^- = 1 \text{ sec}$

 $t_{m(PARTIAL\ DISCHARGE)}$ = 10 sec t_{test} = 12 sec

 $t_{ini} = 60 \text{ sec}$

Method b) Non-destructive Test, 100% Production Test



 $t_3, t_4 = 0.1 \text{ sec}$

 $t_{\text{m(PARTIAL DISCHARGE)}}$ = 1.0 sec t_{test} = 1.2 sec

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
 - Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or i any way allow it to enter the mouth.

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